

Description

The 120N03 is the high cell density trench N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The 120N03 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

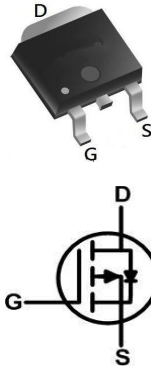
Super Low Gate Charge

100% EAS Guaranteed

Green Device Available

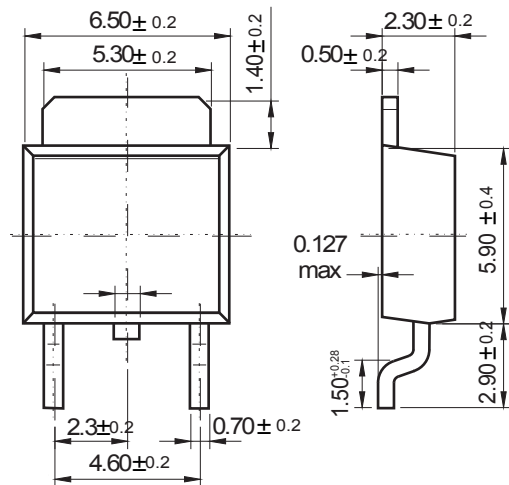
Excellent CdV/dt effect decline

Advanced high cell density Trench technology



TO-252

Unit: mm



Dimensions in inches and (millimeters)

Product Summary

BVDSS	RDSON	ID
30V	2.5mΩ	120 A

Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		10s	Steady State	
V_{DS}	Drain-Source Voltage	30		V
V_{GS}	Gate-Source Voltage	±20		V
$I_D@T_C=25^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^1$	120		A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^1$	75		A
I_{DM}	Pulsed Drain Current ²	384		A
EAS	Single Pulse Avalanche Energy ³	198		mJ
I_{AS}	Avalanche Current	53.8		A
$P_D@T_C=25^{\circ}C$	Total Power Dissipation ⁴	62.5		W
$P_D@T_A=25^{\circ}C$	Total Power Dissipation ⁴	6	2.42	W
T_{STG}	Storage Temperature Range	-55 to 175		°C
T_J	Operating Junction Temperature Range	-55 to 175		°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	62	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹ (t ≤ 10s)	---	25	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	2.4	°C/W

120N03

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

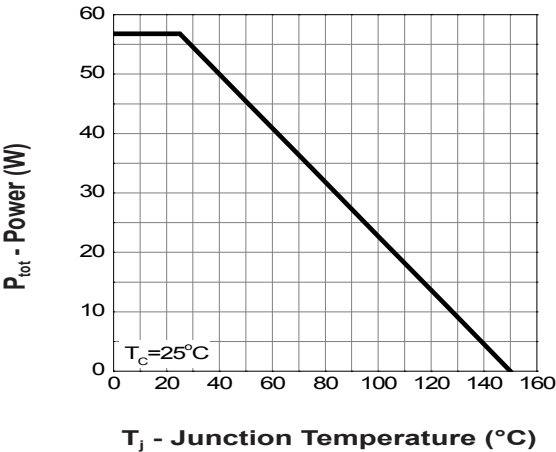
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =24V, V _{GS} =0V T _J =85°C	-	-	1 30	μA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250μA	1.4	1.7	2.5	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)} ^d	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =20A T _J =125°C	-	2.5 4.4	3.8 -	mΩ
Gfs	Forward Transconductance	V _{DS} =5V, I _{DS} =10A	-	24.6	-	S
Diode Characteristics						
V _{SD} ^d	Diode Forward Voltage	I _{SD} =20A, V _{GS} =0V	-	0.8	1.1	V
t _{rr}	Reverse Recovery Time	I _{DS} =20A, dI _{SD} /dt=100A/μs	-	35.6	-	ns
t _a	Charge Time		-	19.3	-	
t _b	Discharge Time		-	16.3	-	
Q _{rr}	Reverse Recovery Charge		-	26	-	nC
Dynamic Characteristics ^e						
R _G	Gate Resistance	V _{GS} =0V,V _{DS} =0V,F=1MHz	-	1	2	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, Frequency=1.0MHz	-	2485	2971	pF
C _{oss}	Output Capacitance		-	850	-	
C _{rss}	Reverse Transfer Capacitance		-	85	-	
t _{d(ON)}	Turn-on Delay Time	V _{DD} =15V, R _L =15Ω, I _{DS} =1A, V _{GEN} =10V, R _G =6Ω	-	12.4	23	ns
t _r	Turn-on Rise Time		-	9.5	18	
t _{d(OFF)}	Turn-off Delay Time		-	27.2	49	
t _f	Turn-off Fall Time		-	35.2	64	
Gate Charge Characteristics ^e						
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =10V, I _{DS} =20A	-	20.6	28.8	nC
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =4.5V, I _{DS} =20A	-	9.8	-	
Q _{gth}	Threshold Gate Charge		-	1.8	-	
Q _{gs}	Gate-Source Charge		-	3.8	-	
Q _{gd}	Gate-Drain Charge		-	3.7	-	

Note d : Pulse test ; pulse width≤300μs, duty cycle≤2%.

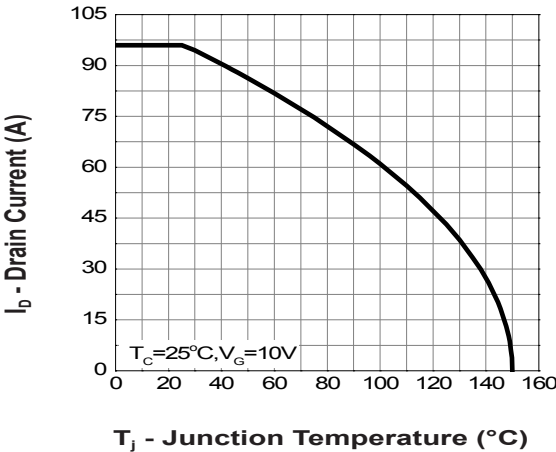
Note e : Guaranteed by design, not subject to production testing.

RATING AND CHARACTERISTIC CURVES (120N03)

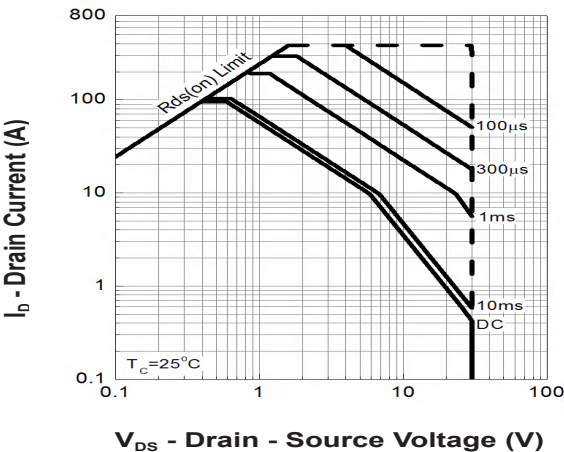
Power Dissipation



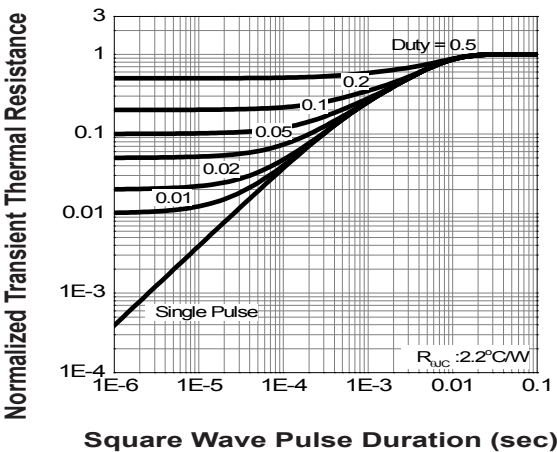
Drain Current



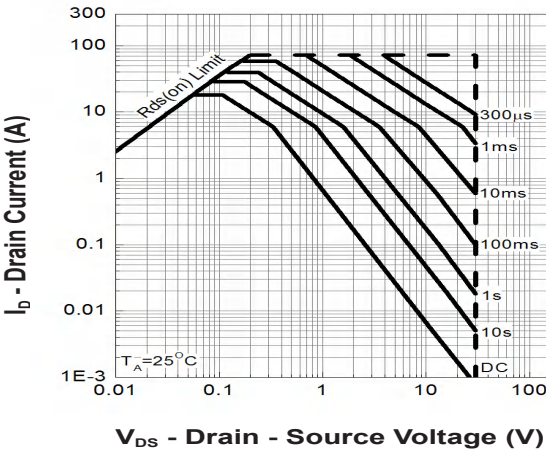
Safe Operation Area



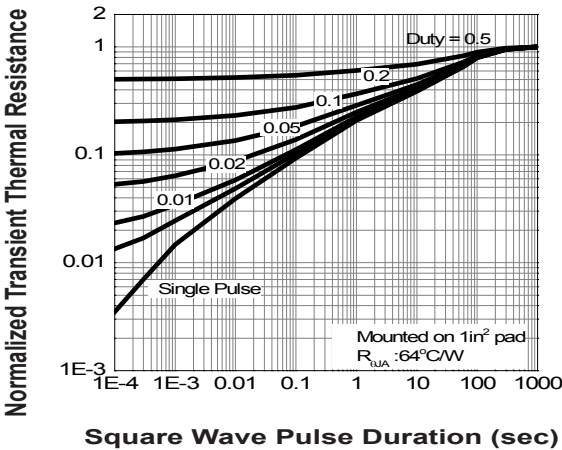
Thermal Transient Impedance



Safe Operation Area

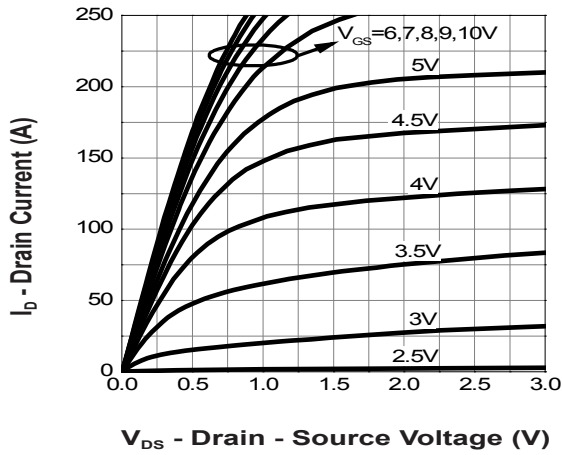


Thermal Transient Impedance

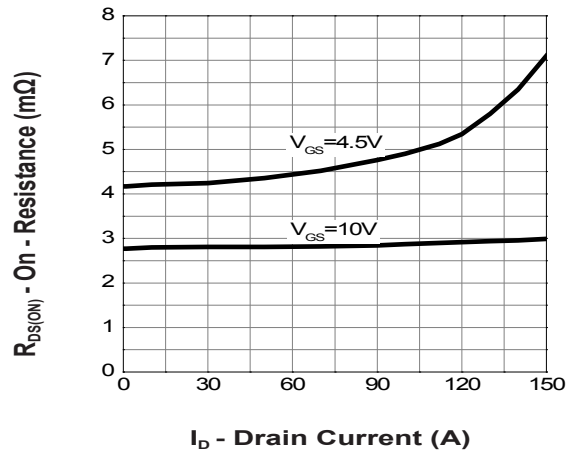


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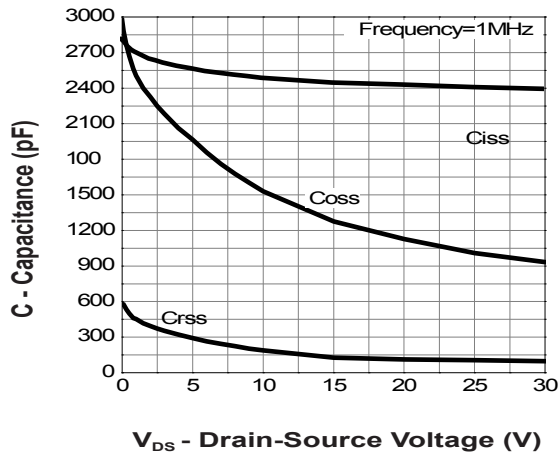
Output Characteristics



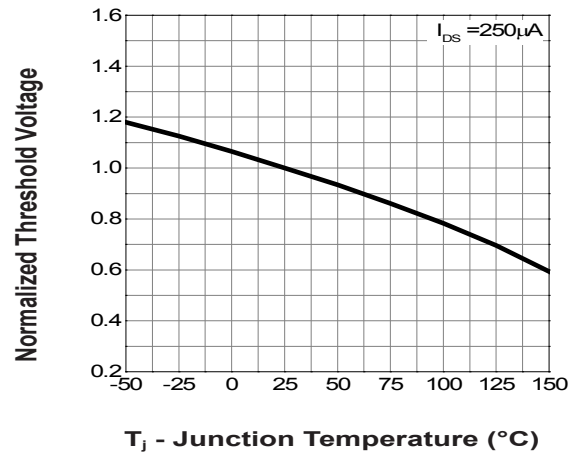
Drain-Source On Resistance



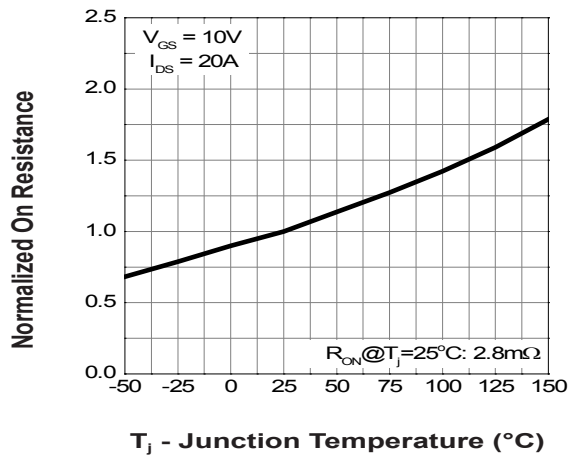
Capacitance



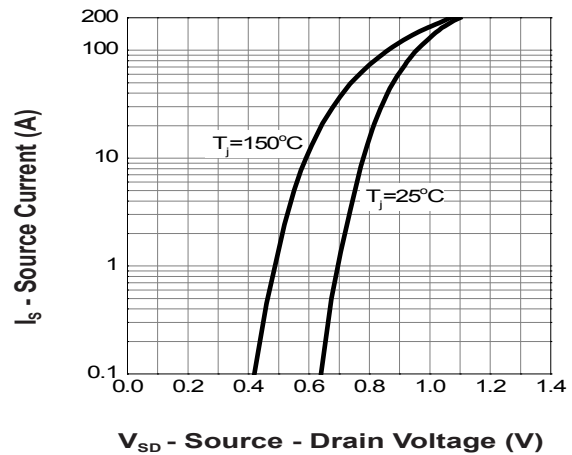
Gate Threshold Voltage



Drain-Source On Resistance



Source-Drain Diode Forward



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